

Product Change Notification



Product Group: DD/Mon Nov 7, 2022/PCN-DD-029-2022-REV-0

IGBT wafer diameter change and materials consolidation in Power Modules

DESCRIPTION OF CHANGE: Vishay Semiconductors announces the wafer diameter change from 8" to 12" of IGBT chips used in below power modules.

Taking the chance of this announcement, Vishay also communicates qualified materials to be used in some of the listed Part Number to support customers demand (See details in Annex1).

REASON FOR CHANGE: Obsolescence of 8 inches wafer from IGBT supplier and supply chain securement.

EXPECTED INFLUENCE ON QUALITY/RELIABILTY/PERFORMANCE: There will be no effect on product quality, reliability or performance.

PART NUMBERS/SERIES/FAMILIES AFFECTED: Please see materials list on the succeeding page.

VISHAY BRAND(s): Vishay Semiconductors

TIME SCHEDULE:

Start Shipment Date: Wed Jan 11, 2023

SAMPLE AVAILABILITY: Samples available upon request

PRODUCT IDENTIFICATION: Batch code (contact factory for the details)

QUALIFICATION DATA: Available upon request

This PCN is considered approved, without further notification, unless we receive specific customer concerns before Tue Jan 10, 2023 or as specified by contract.

ISSUED BY: Fabio Bertuccio, fabio.bertuccio@vishay.com

For further information, please contact your regional Vishay office.

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VS-S1815	VS-S1816	VS-S1645A	VS-GT80DA120U	VS-GT100DA120UF
VS-GT180DA120U				

ANNEX 1

Package	Part Number	Implemented Change
	VS-S1815	- 8" to 12" IGBT wafer diameter conversion.
Econo 2	VS-S1816	 Additional housing material already announced in PCN-DD-011-2021 for other packages.
DIAP	VS-S1645A	 8" to 12" IGBT wafer diameter conversion. Change from existing solder preform to Pb-free solder paste material for die soldering process.
	VS-GT80DA120U	- 8" to 12" IGBT wafer diameter conversion
SOT-227	VS-GT100DA120UF	- Additional substrate material already announced in PCN-DD-010-2022
	VS-GT180DA120U	for other part numbers in SOT-227